AI4DI Newsletter No.7

INDUSTRIAL MACHINERY
AUTOMOTIVE
SEMICONDUCTOR
FOOD AND BEVERAGE
TRANSPORTATION

Newsletter No.7
December 2022

INSIDE THIS ISSUE

- European Forum for Electronic Components and Systems – EFECS 2022 in Amsterdam

- AI4DI booth at EFECS 2022

- AI4DI Publications

OVERVIEW

Start date:	1 May 2019
Duration:	43 months
Total budget:	30 M€
EU budget contribution:	8.8 M€
National budget contribution:	8 M€
Number of participants:	41

About AI4DI

AI4DI's mission is bringing AI from the cloud to the edge and making Europe a leader in silicon-born AI by advancing Moore's law and accelerating edge processing adoption in different industries through reference demonstrators.

AI4DI's objective is to research and develop AI technologies implemented to different industrial sector applications and deployed under conditions as close as possible to real life.

The project aims to enhance processes based on repetitive tasks, focusing on replacing process identification and validation methods with intelligent technologies across the automotive, semiconductor, machinery, food and beverage, and transportation industries.

The project aims to provide AI-based technologies at the edge for digitising the industry by reducing costs, saving time, and increasing quality by enhancing industrial processes.

AI4DI's advancements enable optimising/improving the industrial processes, products, and services and support building and sustaining a dynamic AI technology ecosystem in Europe.

ECSEL Joint Undertaking
Electronic Components and Systems for European Leadership

European Forum for Electronic Components and Systems – EFECS 2022

The **European Forum for Electronic Components and Systems – EFECS** is the international forum to Create impact through collaborative innovation. For autonomous and sustainable European Electronic Components and Systems value chains. This year, the event organisers, AENEAS, EPoSS and Inside, have joined forces to bring all stakeholders together on the 24th -25th of November 2022 in Amsterdam at Beurs van Berlage, where we come together to Create impact through Collaborative Innovation.

ECS-SRIA 2022 was also part of EFECS 2022, as a fifth edition and an update of the ECS Strategic Research and Innovation Agenda (ECS-SRIA), jointly developed by the members of the three industry associations: AENEAS, EPoSS and Inside. This edition was the basis for proposals for KDT Call 2 and Xecs call 2. It describes the Major Challenges and priorities and the necessary R&D&I efforts to tackle them in the area of the electronics components and systems, and systems of systems, spanning the entire ECS value chain, from foundational and cross-sectional technologies to application fields.

AI4DI project was presented to over 600 participants of the EFECS 2022 with a project booth, informing the community via videos, posters, roll-up, flyers, brochures, and even branded AI4DI chocolates!
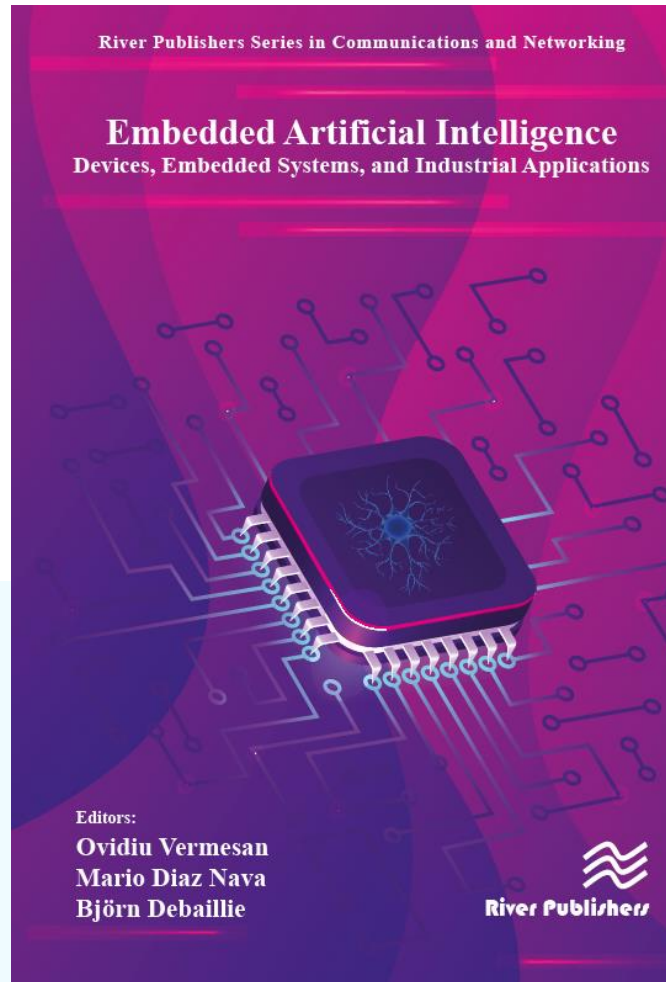
AI4DI project booth at EFECS 2022:

The AI4DI project booth attracted many visitors throughout the event's two days. The visitors enjoyed the project's animated videos, joined discussions about industrial applications, and learned about the project's 23 demonstrators.

AI4DI Publications

The fourth project book – "Embedded Artificial Intelligence: Devices, Embedded Systems, and Industrial Applications" – will be published as a result of the collaboration with ANDANTE and TEMPO ECSEL JU projects!

River Publishers Series in Communications and Networking

Embedded Artificial Intelligence
Devices, Embedded Systems, and Industrial Applications

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